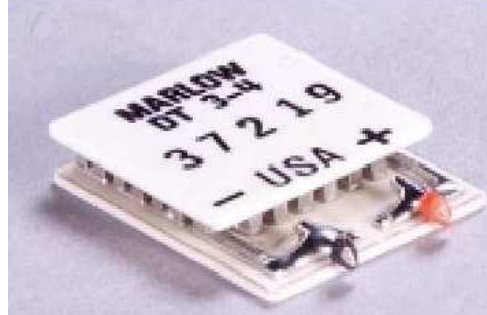


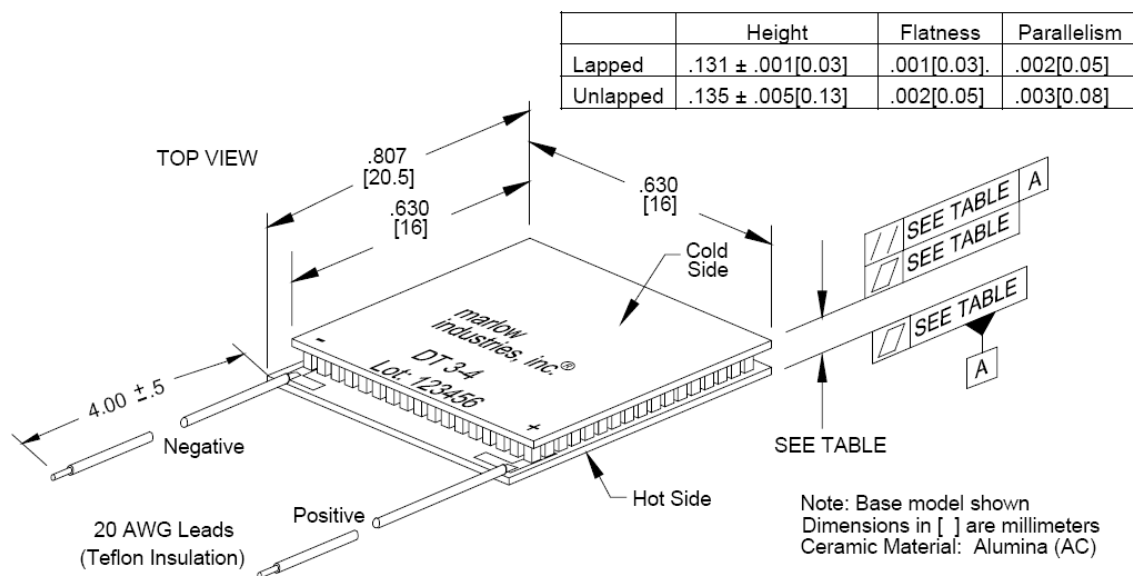
THERMOELECTRIC COOLER 3-4

Performance Values

Hot Side Temperature (°C)	27°C	50°C
ΔT_{max} (°C-dry N ₂)	65	73
Q _{max} (watts)	9	10
I _{max} (amps)	3.7	3.7
V _{max} (vdc)	3.6	4.1
AC Resistance (ohms)	0.8	- - -



Mechanical Characteristics



Ordering Options

Description
Base Model
Lapped Model
Sealed Model
Lapped and Sealed Model

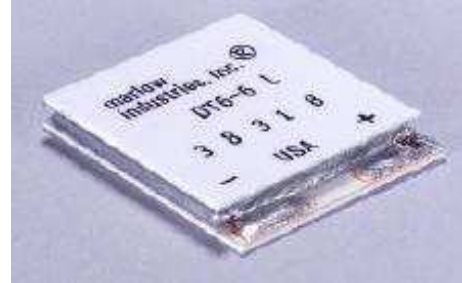
Features

- Solid state reliability
- Built with high temperature solder with the ability to withstand higher assembly processing temperatures for short periods of time (<160°C)
- Superior nickel diffusion barriers on elements
- High strength for rugged environment
- Porched configuration for improved leadwire strength
- RTV sealing option available to improve reliability in condensing environment
- Lapped option available for multiple module applications.

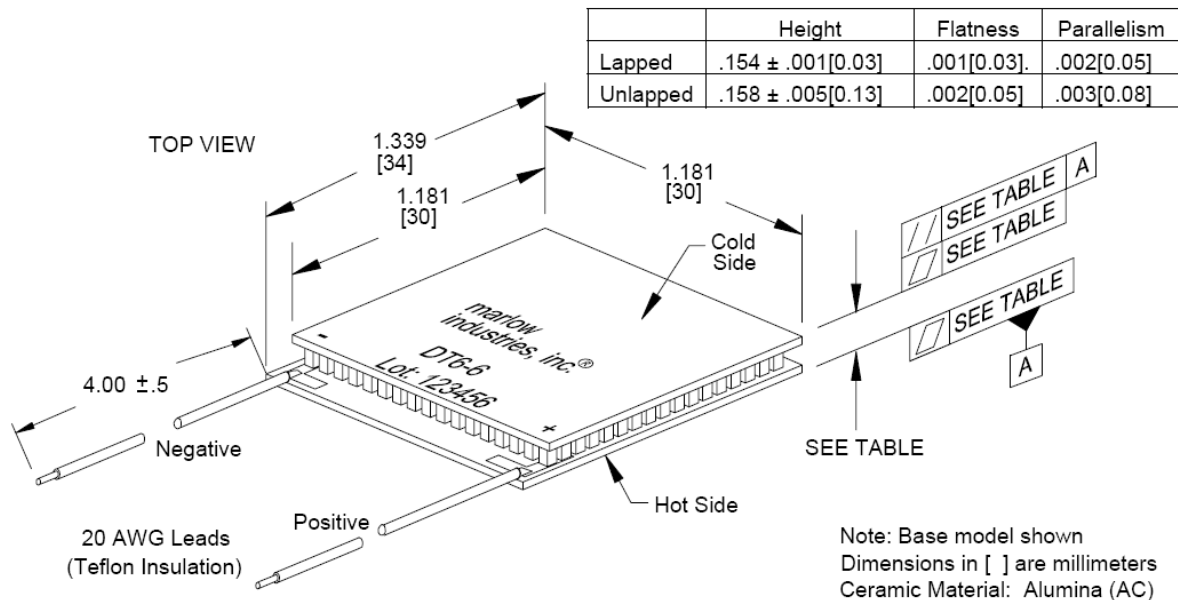
THERMOELECTRIC COOLER 6-6

Performance Values

Hot Side Temperature (°C)	27°C	50°C
ΔT_{max} (°C-dry N ₂)	65	73
Q _{max} (watts)	30	33
I _{max} (amps)	5.6	5.6
V _{max} (vdc)	8.2	9.2
AC Resistance (ohms)	1.2	- - -



Mechanical Characteristics



Ordering Options

Description
Base Model
Lapped Model
Sealed Model
Lapped and Sealed Model

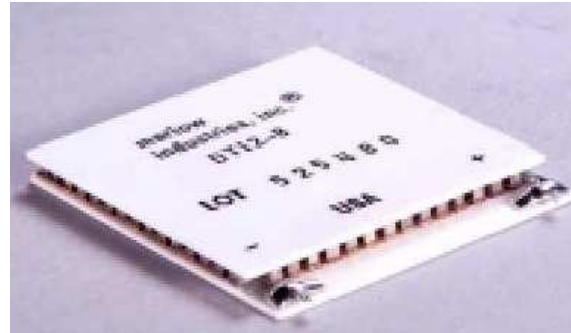
Features

- Solid state reliability
- Built with high temperature solder with the ability to withstand higher assembly processing temperatures for short periods of time (<160°C)
- Superior nickel diffusion barriers on elements
- High strength for rugged environment
- Porched configuration for improved leadwire strength
- RTV sealing option available to improve reliability in condensing environment
- Lapped option available for multiple module applications.

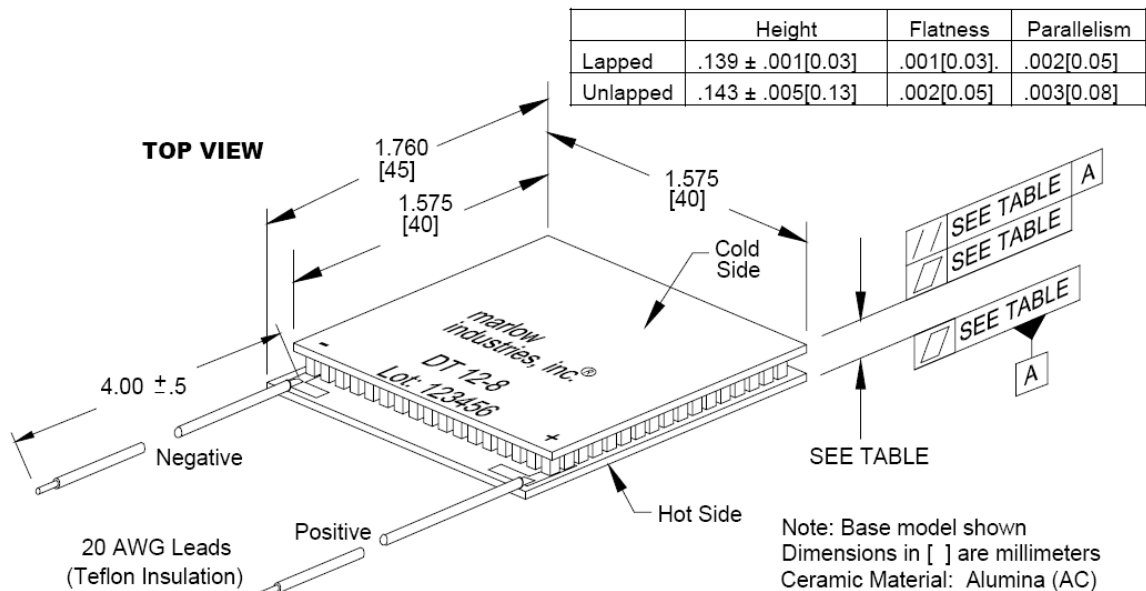
THERMOELECTRIC COOLER 12-8

Performance Values

Hot Side Temperature (°C)	27°C	50°C
ΔTmax (°C-dry N ₂)	66	74
Qmax (watts)	71	78
I _{max} (amps)	7.4	7.4
V _{max} (vdc)	14.7	16.4
AC Resistance (ohms)	1.6	---



Mechanical Characteristics



Ordering Options

Description
Base Model
Lapped Model
Sealed Model
Lapped and Sealed Model

Features

- Solid state reliability
- Built with high temperature solder with the ability to withstand higher assembly processing temperatures for short periods of time (<160°C)
- Superior nickel diffusion barriers on elements
- High strength for rugged environment
- Porched configuration for improved leadwire strength
- RTV sealing option available to improve reliability in condensing environment
- Lapped option available for multiple module applications.